

Product Name: TB6641FTG

Package Name: VQFN32

1. Thermal tests

Test Item	Test Condition	Failure Size / Sample Size
Resistance to Soldering Heat for Packages	Reflow peak temperature and moisture soak conditions are specified per package type. 3 times	0 / 32
Temperature Cycling	-65deg.C (20min) to 25deg.C to 150deg.C (20min) to 25deg.C 300 cycles	0 / 32
-	-	-
-	-	-

2. Mechanical tests

Test Item	Test Condition	Failure Size / Sample Size
Solderability	Solder temperature : 245deg.C for Solder type Sn-3Ag-0.5Cu Solder immersion time : 5s ,Flux type : active flux 1 time	0 / 22
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-	-	-
-	-	-
-	-	-

3. Life tests

Test Item	Test Condition	Failure Size / Sample Size
High Temperature Operating Life	Max operating temperature, Max operating voltage ,1000h	0 / 32
High Temperature Storage Life	Max storage temperature ,1000h	0 / 32
High Temperature High Humidity Bias	Ta=85deg.C, RH=85%, Max operating voltage ,1000h	0 / 32
Autoclave	Ta=121deg.C, RH=100%, 203kPa ,96h	0 / 32
-	-	-
-	-	-

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1.Reflow

Number: 3 times maximum

Peak : 260 deg.C

Reflow zone : 255 deg.C within 30 seconds, 217 deg.C 60 to 150 seconds

Preheat : 150 to 200 deg.C , 60 to 120 seconds

NOTE: All temperatures refer to the package body surface.

The heat-resistant temperature profile is shown in Fig.1.

The temperatures in this profile are the maximum guaranteed temperatures that the device endures.

Select the temperatures for a pre-heat and a heat most suitable for your solder paste type, etc. within the conditions described in Fig.1.

This package is dry-packed in a moisture barrier bag. After opening the bag, keep the devices at or lower than 30deg.C/ 60%RH and complete a final reflow process within 168hours.

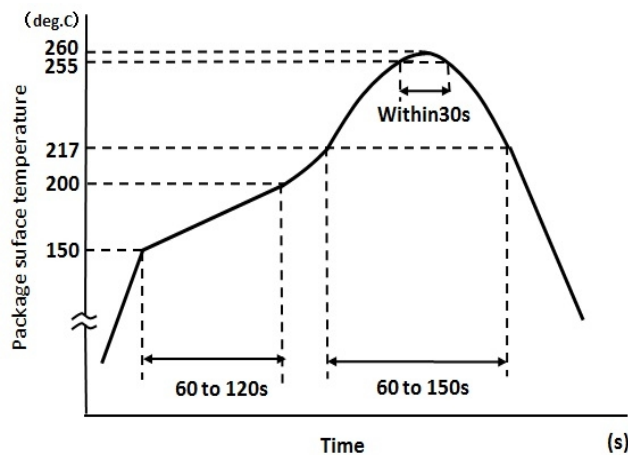


Fig.1 Example of Heat-resistant Temperature Profile

2.Others

We urge you to verify well before mounting to assure enough solder joint strength.

Always solder the Product in accordance with the heat-resistance mounting conditions set forth above. In the event the Product is soldered otherwise, the applicable product warranty, if any, is void.

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